

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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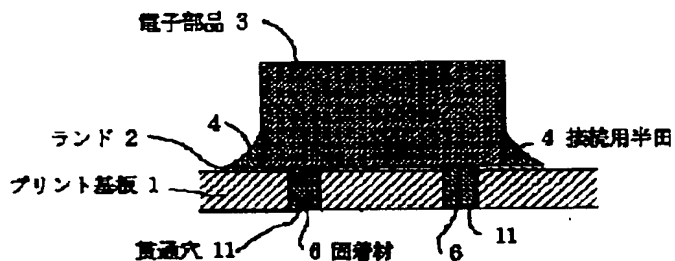
APPLICATION DATE : 14-05-97  
APPLICATION NUMBER : 09140992

APPLICANT : YASKAWA ELECTRIC CORP;

INVENTOR : ZAIZEN TOMOYUKI;

INT.CL. : H05K 3/34 H05K 3/34

TITLE : SURFACE MOUNTING METHOD



ABSTRACT : PROBLEM TO BE SOLVED: To provide a high quality surface mounting method which does not generate failures such as solder removal.

SOLUTION: An electronic component 3 is mounted on a land 2 which is provided on the surface of a printed board 1. In this surface mounting method, a plurality of through holes 11 which penetrate the land 2 on the front surface from the rear side of the printed board 1 are provided, and after soldering the electronic component 3 on the land 2, a through holes 11 are filled with fixing material. Therefore, an unnecessary fixing material that disturbs the surrounding components and wiring and deteriorates cooling performance is eliminated, and breakage is prevented even when vibration and tensile force due to clipping are applied.

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